



Prelaminated inlays Microprocessor



LUX-IDent's products

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A range of applications.

There has been a clear trend in the market over the last few years towards the use of contactless technology employing more and more applications, where only the contact chip was typically used in the past. Due to an increasing demand for chip performance, its functionality and security standards, contactless microprocessor chips with specific OS (Operating System) are used. We can offer chips (incl. chip module and OS) which can be sourced from different suppliers (chip manufacturers and OS developers). We are also ready to process prelaminated inlays made out of consigned modules provided by our clients. Prelaminated inlays are suitable for use in the production of ISO standard cards. LUX-IDent uses a proprietary manufacturing process to produce its prelaminated inlays. Our inlays are very robust and boast unequalled torsion/bending characteristics, extreme durability and optimized read/write performance.

Features

- Very reliable and robust plastic package
- High reading distance optimized to each chip
- Materials: PVC, PETG, PC
- Colour: white or transparent
- Possibility of combining two and more different chip technologies in one prelaminated sheet
- Different sheet formats are available 1×5, 2×5, 3×6, 3×7, 3×8, 3×10, 4×10 up to 640×520 mm, others upon request

Our antenna design allows us (based on specific customer requests) to position an antenna on the sheet layout along the embedding of contact chip module without any interference from the RFID antenna. This is what we call the hybrid card, which combines contactless and contact chip technology into one card.

Example of applications

- city card
- student card
- e-purse systems
- e-ID projects
- public transport
- logical access
- physical access, etc.

Available chip technologies

Manufacturer frequency	Chip type
EM Microelectronic	
LF 125 kHz / 134.2 kHz	EM4102, EM4305, EM4450
NXP	
LF 125 kHz / 134.2 kHz	Hitag 1, Hitag 2, Hitag S 256bit, Hitag S 2048bit
HF 13.56 MHz	Mifare: Ultralight, Ultralight C, Mini, Classic 1K, Classic 4K, Desfire 4K V.06, Desfire 2K EV1, Desfire 4K EV1, Desfire 8K EV1, Plus S 2K, Plus S 4K, Plus X 2K, Plus X 4K I-Code: SL1, SLI-L, SLI, SLI-S SmartMX, JCOP
UHF 840–960 MHz	UCODE G2XL, UCODE G2XM
Infineon	
HF 13.56 MHz	Mifare SLE66R35 1K, My-D: SRF55V02P, SRF55V10P, NFC SLE66R16P, NFC SLE66R32P
Atmel	
LF 125 kHz / 134.2 kHz	ATA5575M1, ATA5575M2, ATA5577, Q5
Inside Secure	
HF 13.56 MHz	Picopass 2K, 32K
Legic	
HF 13.56 MHz	Prime MIM256, Prime MIM1024 Advant: ATC128, ATC256, ATC1024, ATC2048, ATC4096

Other ICs are available upon request.